



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:  
Chung, et al.

Serial No.: 09/965,370

Confirmation No.: 6507

Filed: 09/26/2001

For: Integration Of Barrier Layer  
And Seed Layer

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Group Art Unit: 1762

Examiner: Unknown

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MAIL STOP  
Commissioner for Patents  
P.O. Box 1450  
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CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on June 27, 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.	
Date June 27, 2003	Signature <i>[Signature]</i>

Dear Sir:

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

The Applicants, and the Attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents, publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56.

While the information submitted in this Supplemental Information Disclosure Statement may be material pursuant to 37 CFR § 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

In accordance with 37 CFR § 1.97, this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or

If the sum of \$180.00 is due under 37 CFR § 1.17(p) pursuant to § 1.97, the Commissioner is hereby authorized to charge this fee, and any other fee necessary to make this submission timely, to the Deposit Account No. 20-0782/AMAT/6303/AOP.

Respectfully submitted,

A handwritten signature in cursive script, appearing to read "Ari Pramudji", written over a horizontal line.

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U.S. Department of Commerce, Patent and Trademark Office (PTO Form 1449 modified)		Docket No. AMAT/6303	Serial No. 09/965,370
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>		Applicant Chung, et al.	Confirmation No.: 6507
(Use several sheets if necessary)		Filing Date 09/26/2001	Group 1762
Examiner Unknown			

**U.S. Patent Documents**

*Examiner Initial		Document Number	Issue Date	Applicant(s) Name	Class	Subclass	Filing Date If Appropriate
	A1	5,529,955	06/25/1996	Hibino, et al.	437	195	08/25/1994
	A2						
	A3						
	A4						
	A5						
	A6						
	A7						
	A8						
	A9						
	A10						
	A11						
	A12						
	A13						

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**Foreign Patent Documents**

*Examiner Initial		Document Number	Date	Country	Class	Subclass	Translation	
							YES	NO
	B1						<input type="checkbox"/>	<input type="checkbox"/>
	B2						<input type="checkbox"/>	<input type="checkbox"/>
	B3						<input type="checkbox"/>	<input type="checkbox"/>

**OTHER ART**

*Examiner Initial		Including Author, Title, Date, Pertinent Pages, Etc.
	C1	R.C. Ellwanger, "An Integrated Aluminum/CVD-W Metallization Process For Sub-Micron Contact Filling", June 11-12, 1991 IEEE Catalog No. 91 TH0359-0, pages 41-50.
	C2	Kaanta, et al. "Dual Damascene: A ULSI Wiring Technology" June 11-12, 1991 VMC

Examiner

Date Considered

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant